Tool ID: 507

Tool Location: 124

Equipment Information Sheet

JEOL 6300

Manager:		Calls to staff phones will be automatically forwarded to
Alan R. Bleier	607-254-4931	their cell phones during accessible hours. At other times
Rackeutor Panepucci	607-254-4855	leave a message or send them an email.
Bakk úlpæichler	607-254-4949	SAFETY

No safety concerns during normal operation

USAGE RESTRICTIONS

No buddy system restrictions imposed on normal operation.

Please review electron beam lithography training materials, in AFS, at shares - public - processes_from_cnf_staff - ElectronBeamLithography - TrainingMaterials (accessible on any general use PC or CNF Thin client at CNF)

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- Please put the following information in the Process field in Coral when you make the reservation: the beam current you plan to use, and the objective lens (4 or 5) you plan to use.
- No more than 3 hour reservation between the hours of 8AM 8PM, Monday through Friday
- Maximum 12 hours reserved in advance at any time per person
- The same user, group, or company must have at least 3 hours between any 2 reservations

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds Allowed Not Allowed Tool category 1/1E, 2, 3, and 4 materials Silicon Based Substrates and Films III/V compound Semiconductors Glass Substrates PECVD and ALD Films Cured organics and baked Photoresist CNF Class A, B, and Refractory metals Exposed Gold, Silver, Copper Alkali and Alkaline Compounds Organic/Biology Molecules preparedw/salt buffers High Vapor Pressure Materials (Mg, Ca, * Some tool restrictions on high vapor pressure Zn)*materials may apply Soft organic materials

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Whole silicon wafers only discuss pieces or other materials with managers.
- Conductive path to ground if substrate is insulating, talk to managers.
- Fully baked resists only; do not load samples with unbaked resist or glue or anything that may degas.

Last Updated: 03/27/2024